



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Mahalingam Nandakumar, et al. Art Unit: 2811

Serial No.: 09/876,292

Examiner: TBD

Filed: 06/07/01

Docket: TI-31089

For: Additional n-Type LDD/Pocket Implant for Improving Short-Channel NMOS ESD Robustness

LETTER TO THE OFFICIAL DRAFTSPERSON

#4

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on <u>8-20-01</u>	
as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents Application Processing Division's Customer Correction Branch, Washington, D.C. 20231.	
<u>Karen Vertz</u> Karen Vertz	<u>8-20-01</u> Date

Assistant Commissioner for
Patents
Washington, D. C. 20231

Dear Sir:

Enclosed are **FOUR (4)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated
P.O. Box 655474 M/S 3999
Dallas, Texas 75265
(972) 238-7160

Respectfully submitted,

Gary C. Honeycutt
Gary C. Honeycutt
Reg. No. 20,250
Attorney for Applicants

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